

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph on page 16, line 12 with the following amended paragraph:

As a typical process of preparing the organic film 36, a 0.5-1 μm thick polyimide film is formed. Specifically, polyimide is coated on the upper face of the substrate by a spin coater, and then the coating is pre-baked on a hot plate at 50°C for 30 minutes and then at 125°C for 3 minutes. Then a positive resist layer is formed on the pre-baked ~~polyimide~~ polyimide film by rotary coating or a similar method. This positive resist layer is subjected to exposure and development to form three holes corresponding to the connecting holes 36a to 36c. As a result of this development process, three holes are formed in the positive resist layer and the polyimide film is etched by the developing solution with the positive resist layer as a mask so that the connecting holes 36a to 36c are formed in the polyimide film as the organic film 36 as shown in Figs. 3A and 13.